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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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HSB88WK

Silicon Schottky Barrier Diode for High Speed Switching

ADE-208-1042 (Z)

Rev. 0
Jan. 2001

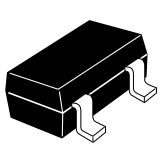
Features

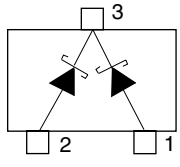
- Proof against high voltage.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSB88WK	C4	CMPAK

Pin Arrangement





(Top View)

1. Anode
2. Anode
3. Cathode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Average rectified current	I_O*[1]	15	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Note: Per one device.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	350	—	420	mV	I_F = 1 mA
	V_{F2}	500	—	580		I_F = 10 mA
Reverse current	I_{R1}	—	—	0.2	μA	V_R = 2V
	I_{R2}	—	—	10		V_R = 10V
Capacitance	C	—	—	0.80	pF	V_R = 0V, f = 1 MHz
Capacitance deviation	ΔC	—	—	0.10	pF	V_R = 0V, f = 1 MHz
Forward voltage deviation	ΔV_F	—	—	10	mV	I_F = 10 mA
ESD-Capability *[1]	—	30	—	—	V	C = 200 pF, R = 0 Ω, Both forward and reverse direction 1 pulse.

Note: Failure criterion ; IR > 0.4μA at VR = 2 V

Main Characteristic

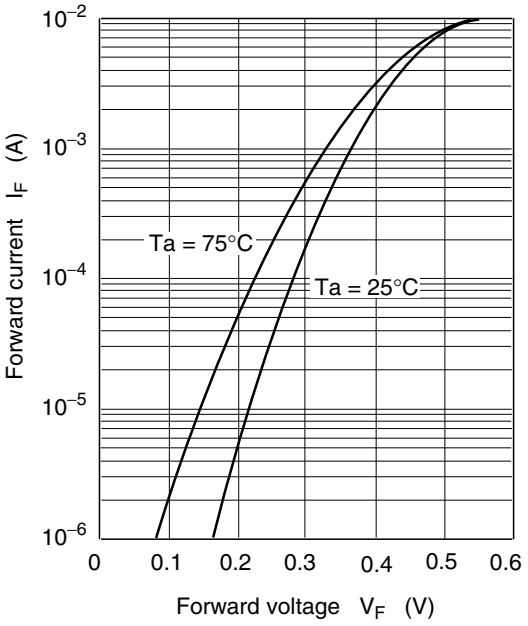


Fig.1 Forward current Vs. Forward voltage

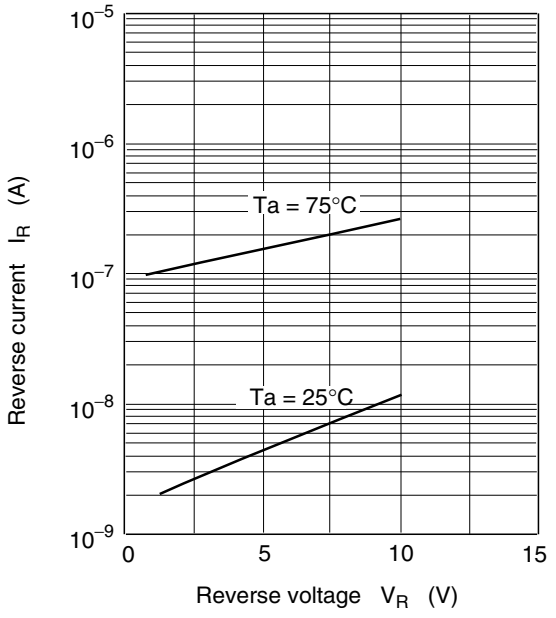


Fig.2 Reverse current Vs. Reverse voltage

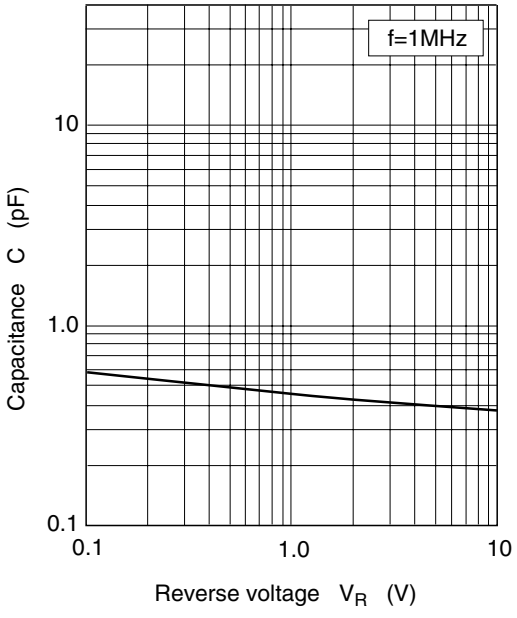
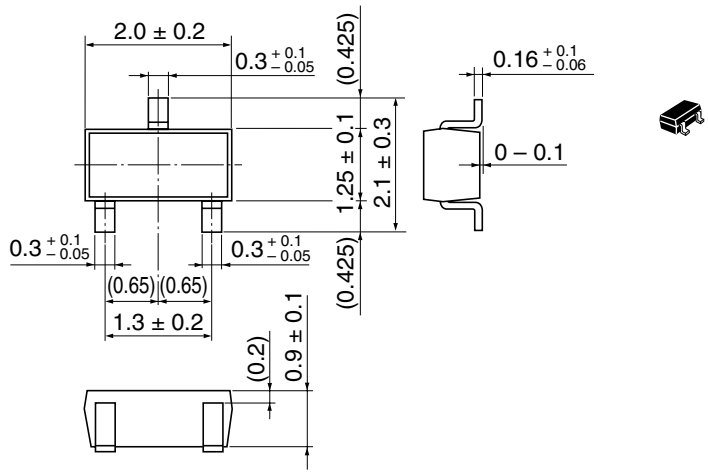


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



Hitachi Code	CMPAK
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.006 g

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